



Grand Venture Technology Limited

(Company Registration Number 201222831E)

NEWS RELEASE

GVT ACCELERATES FRONT-END SEMICONDUCTOR EXPANSION WITH KEY WINS FROM GLOBAL LEADERS IN TRANSFORMATIVE PROJECTS SUCH AS TSV

- Through-Silicon VIA is a key technology used in Advanced Packaging and High Bandwidth Memory to achieve high-density integration and superior performance
- Breakthrough project showcases GVT's role in next-generation semiconductor manufacturing for high-value applications
- Recent front-end wins are expected to drive new opportunities and position GVT for multi-year revenue growth starting 2025

Singapore, January 23, 2024 – Mainboard-listed **Grand Venture Technology Limited** (杰纬特科技有限公司, "GVT", or the "Group"), a regional precision manufacturing solutions provider, is proud to announce that the Group has been awarded a pivotal Through-Silicon VIA ("TSV") project by a global leader in wafer fabrication equipment and services to manufacture components and modules.

This is a major milestone in GVT's strategic expansion into the front-end semiconductor market and underscores GVT's growing expertise in critical semiconductor front-end manufacturing processes, including etch, metrology and deposition. This breakthrough reaffirms GVT's position as a trusted partner in enabling advanced chip manufacturing production for high-value applications.

TSV technology pertains to a critical leap in semiconductor manufacturing that enables the delivery of exceptional levels of performance and efficiency. With its ability to allow for high-density stacking and direct vertical connections, TSV is a foundational technology for next generation chips that powers high-value and fast-growing segments such as artificial intelligence, IoT and advanced computing.

With our latest wins and accompanying milestone, GVT is on track to deepen its engagement in the fast-growing front-end semiconductor market. The Company remains committed to leverage on its technical capabilities to deliver innovative and high-quality solutions that meet the constantly

evolving needs of the semiconductor industry. These achievements are expected to contribute to GVT's long-term growth.

We anticipate our recent success in front-end semiconductor to play a key role in driving new opportunities and revenue growth momentum starting from 2025 onwards.

The pivot toward next-generation front-end processes is driving the growth of the front-end equipment market. As forecasted by Yole Intelligence, the Advanced Packaging (“AP”) market is expected to grow at a CAGR₂₃₋₂₉ of 11% to reach US\$69.5 billion in 2029.¹ Additionally, the 2.5D and 3D advanced packaging sector is projected to maintain a robust CAGR₂₃₋₂₉ of 18% to reach US\$27.6 billion in 2029.²

Within this sector, high-end performance packaging, which relies on foundational technologies like TSVs, is expected to grow even faster at a CAGR of 37%, reaching over US\$28 billion by 2029.³

GVT's strategic expansion into front-end semiconductor manufacturing, including TSV technology, positions the Group to capitalize on these opportunities, addressing the needs of next-generation chip production.

Chief Executive Officer Julian Ng (吴伟贤) said, “This pivotal win is well aligned with our strategic customer engagements. We expect our growing involvement in critical technologies such as TSV to further enhance our capabilities and processes. Our investments in innovation and operational excellence are starting to yield tangible results, and we are excited about the future potential for our front-end semiconductor business.”

¹ Yole Intelligence July 2024

² Bloomberg Intelligence: Downturn for Chip-Assembly Tools; TCB a Bright Spot

³ Yole Intelligence June 2024

About Grand Venture Technology Limited (“GVT”)

Founded in 2012, GVT is a fast-growing and trusted solutions and services provider for the manufacture of complex precision machining, sheet metal components and mechatronics modules. Its manufacturing plants in Singapore, Penang and Johor (Malaysia), and Suzhou (China) are backed by the latest automated manufacturing technologies, Class 10,000 cleanroom facilities and a certified quality management system. The Group’s highly experienced and dedicated team of engineering talent serves a strong global network of established partners and suppliers with a wide range of engineering, assembly, testing and product life cycle management solutions.

GVT’s portfolio of customers hail from the semiconductor, electronics, analytical life sciences, aerospace, medical and industrial automation industries, and represent some of the largest OEMs in their respective markets. GVT is listed on the Singapore Exchange Mainboard. Visit <http://www.gvt.com.sg> for more information.

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